

MMSZ4678T1 Series

Zener Voltage Regulators

500 mW SOD-123 Surface Mount

Three complete series of Zener diodes are offered in the convenient, surface mount plastic SOD-123 package. These devices provide a convenient alternative to the leadless 34-package style.

Specification Features:

- 500 mW Rating on FR-4 or FR-5 Board
- Wide Zener Reverse Voltage Range – 1.8 V to 43 V
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (>16 KV) per Human Body Model

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic case

FINISH: Corrosion resistant finish, easily solderable

MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

POLARITY: Cathode indicated by polarity band

FLAMMABILITY RATING: UL94 V-0

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Total Power Dissipation on FR-5 Board, (Note 1.) @ $T_L = 75^\circ\text{C}$ Derated above 75°C	P_D	500 6.7	mW mW/ $^\circ\text{C}$
Thermal Resistance – Junction to Ambient (Note 2.)	$R_{\theta JA}$	340	$^\circ\text{C/W}$
Thermal Resistance – Junction to Lead (Note 2.)	$R_{\theta JL}$	150	$^\circ\text{C/W}$
Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

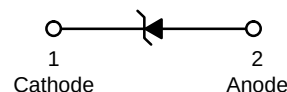
1. FR-5 = 3.5 X 1.5 inches, using the On minimum recommended footprint as shown in Figure 11

2. Thermal Resistance measurement obtained via infrared Scan Method



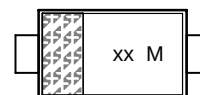
ON Semiconductor®

<http://onsemi.com>



SOD-123
CASE 425
STYLE 1

MARKING DIAGRAM



xx = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device †	Package	Shipping
MMSZ4xxxT1	SOD-123	3000/Tape & Reel
MMSZ4xxxT3*	SOD-123	10,000/Tape & Reel

*MMSZ4703T1 and MMSZ4711T1 Not Available in 10,000/Tape & Reel

DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

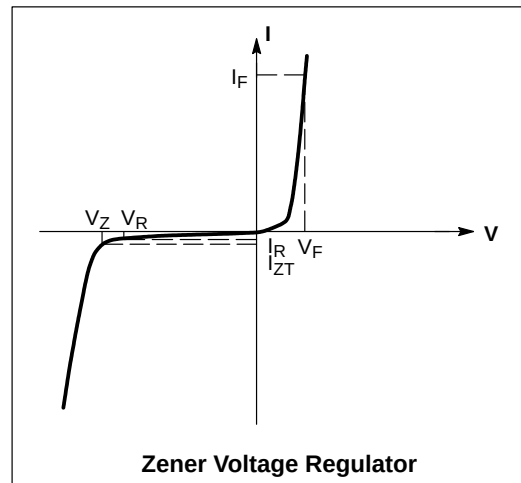
Devices listed in **bold, italic** are ON Semiconductor **Preferred** devices. Preferred devices are recommended choices for future use and best overall value.

†The "T1" suffix refers to an 8 mm, 7 inch reel.
The "T3" suffix refers to an 8 mm, 13 inch reel.

MMSZ4678T1 Series

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.95\text{ V Max. @ } I_F = 10\text{ mA}$)

Symbol	Parameter
V_Z	Reverse Zener Voltage @ I_{ZT}
I_{ZT}	Reverse Current
I_R	Reverse Leakage Current @ V_R
V_R	Reverse Voltage
I_F	Forward Current
V_F	Forward Voltage @ I_F



MMSZ4678T1 Series

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.9\text{ V Max.}$ @ $I_F = 10\text{ mA}$)

Device	Device Marking	Zener Voltage (Notes 1)				Leakage Current	
		V_Z (Volts)			@ I_{ZT}	I_R @ V_R	
		Min	Nom	Max	μA	μA	Volts
MMSZ4678T1	CC	1.71	1.8	1.89	50	7.5	1
MMSZ4679T1	CD	1.90	2.0	2.10	50	5	1
MMSZ4680T1	CE	2.09	2.2	2.31	50	4	1
MMSZ4681T1	CF	2.28	2.4	2.52	50	2	1
MMSZ4682T1	CH	2.565	2.7	2.835	50	1	1
MMSZ4683T1	CJ	2.85	3.0	3.15	50	0.8	1
MMSZ4684T1	CK	3.13	3.3	3.47	50	7.5	1.5
MMSZ4685T1	CM	3.42	3.6	3.78	50	7.5	2
MMSZ4686T1	CN	3.70	3.9	4.10	50	5	2
MMSZ4687T1	CP	4.09	4.3	4.52	50	4	2
MMSZ4688T1	CT	4.47	4.7	4.94	50	10	3
MMSZ4689T1	CU	4.85	5.1	5.36	50	10	3
MMSZ4690T1	CV	5.32	5.6	5.88	50	10	4
MMSZ4691T1	CA	5.89	6.2	6.51	50	10	5
MMSZ4692T1	CX	6.46	6.8	7.14	50	10	5.1
MMSZ4693T1	CY	7.13	7.5	7.88	50	10	5.7
MMSZ4694T1	CZ	7.79	8.2	8.61	50	1	6.2
MMSZ4695T1	DC	8.27	8.7	9.14	50	1	6.6
MMSZ4696T1	DD	8.65	9.1	9.56	50	1	6.9
MMSZ4697T1	DE	9.50	10	10.50	50	1	7.6
MMSZ4698T1	DF	10.45	11	11.55	50	0.05	8.4
MMSZ4699T1	DH	11.40	12	12.60	50	0.05	9.1
MMSZ4700T1	DJ	12.35	13	13.65	50	0.05	9.8
MMSZ4701T1	DK	13.30	14	14.70	50	0.05	10.6
MMSZ4702T1	DM	14.25	15	15.75	50	0.05	11.4
MMSZ4703T1*	DN	15.20	16	16.80	50	0.05	12.1
MMSZ4704T1	DP	16.15	17	17.85	50	0.05	12.9
MMSZ4705T1	DT	17.10	18	18.90	50	0.05	13.6
MMSZ4706T1	DU	18.05	19	19.95	50	0.05	14.4
MMSZ4707T1	DV	19.00	20	21.00	50	0.01	15.2
MMSZ4708T1	DA	20.90	22	23.10	50	0.01	16.7
MMSZ4709T1	DX	22.80	24	25.20	50	0.01	18.2
MMSZ4710T1	DY	23.75	25	26.25	50	0.01	19.0
MMSZ4711T1*	EA	25.65	27	28.35	50	0.01	20.4
MMSZ4712T1	EC	26.60	28	29.40	50	0.01	21.2
MMSZ4713T1	ED	28.50	30	31.50	50	0.01	22.8
MMSZ4714T1	EE	31.35	33	34.65	50	0.01	25.0
MMSZ4715T1	EF	34.20	36	37.80	50	0.01	27.3
MMSZ4716T1	EH	37.05	39	40.95	50	0.01	29.6
MMSZ4717T1	EJ	40.85	43	45.15	50	0.01	32.6

1. Nominal Zener voltage is measured with the device junction in thermal equilibrium at $T_L = 30^\circ\text{C} \pm 1^\circ\text{C}$

*Not Available in the 10,000/Tape & Reel.

MMSZ4678T1 Series

TYPICAL CHARACTERISTICS

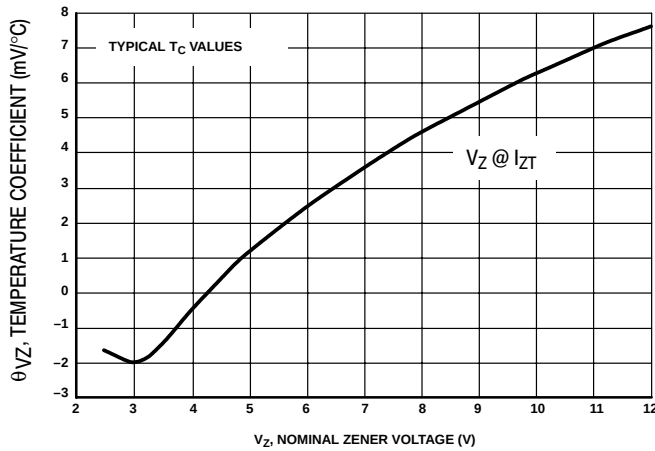


Figure 1. Temperature Coefficients
(Temperature Range -55°C to +150°C)

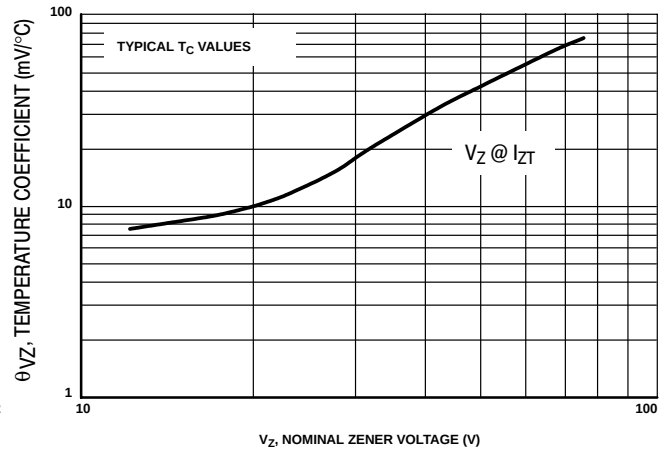


Figure 2. Temperature Coefficients
(Temperature Range -55°C to +150°C)

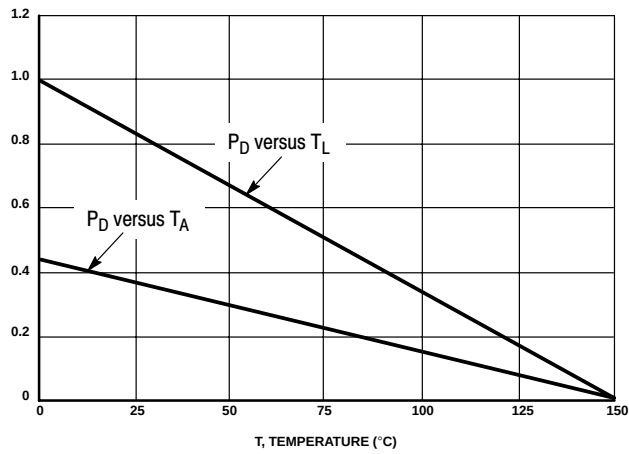


Figure 3. Steady State Power Derating

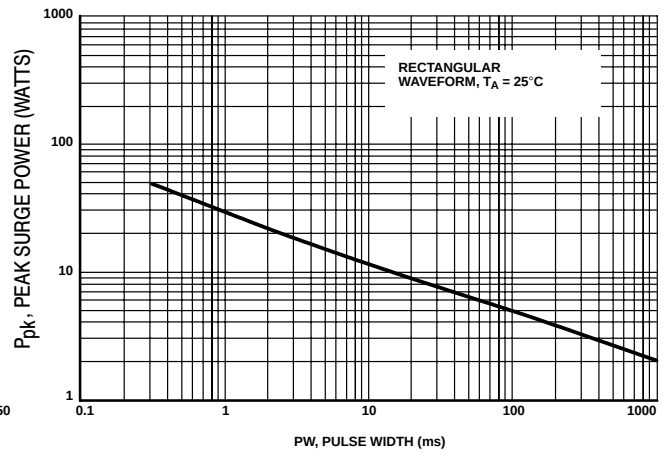


Figure 4. Maximum Nonrepetitive Surge Power

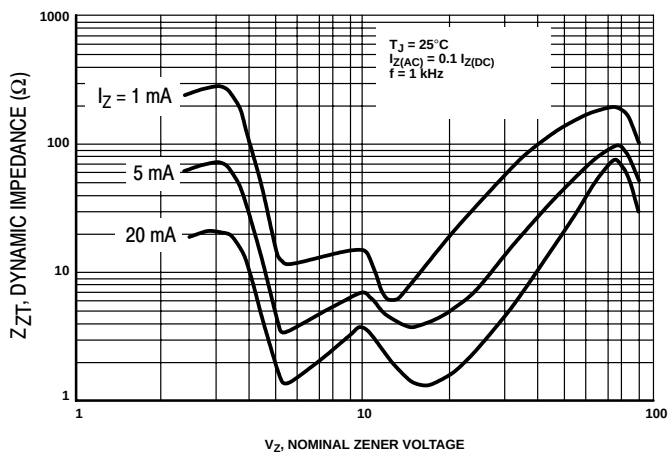


Figure 5. Effect of Zener Voltage on
Zener Impedance

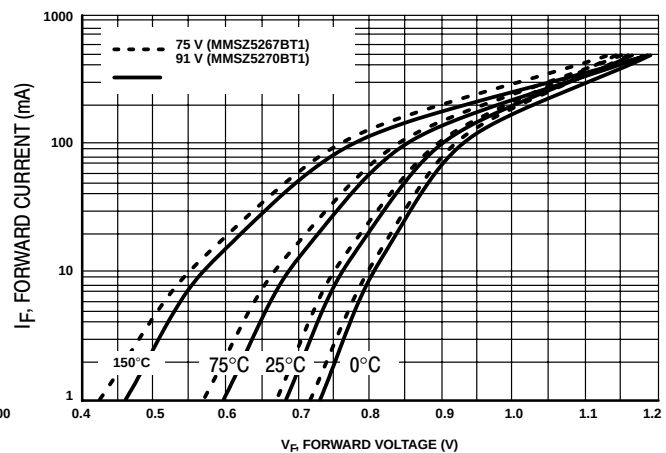


Figure 6. Typical Forward Voltage

MMSZ4678T1 Series

TYPICAL CHARACTERISTICS

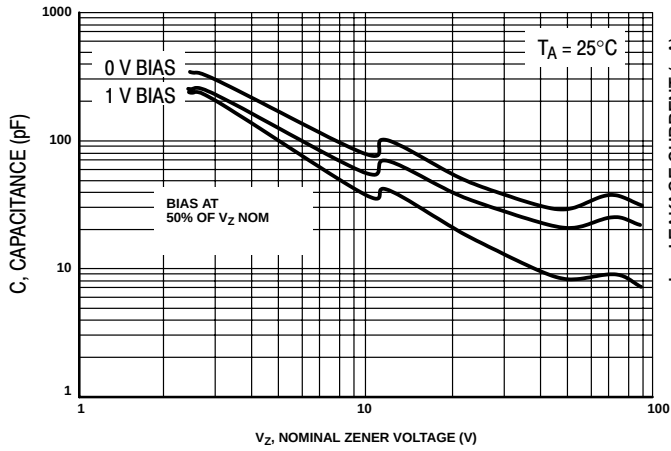


Figure 7. Typical Capacitance

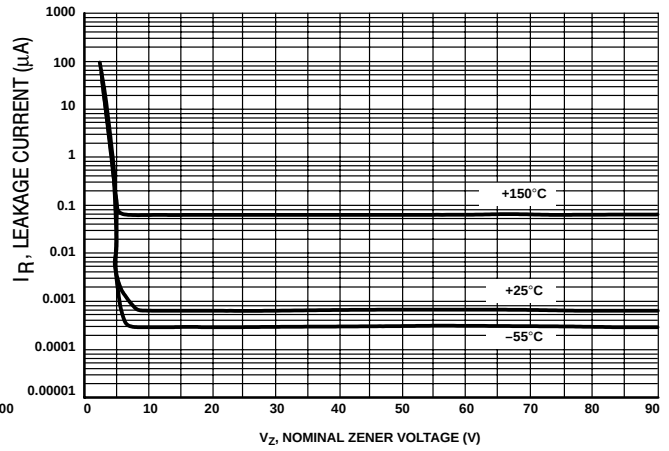


Figure 8. Typical Leakage Current

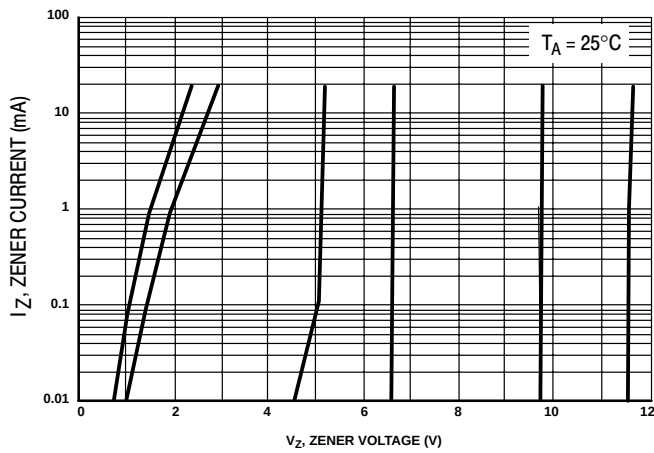


Figure 9. Zener Voltage versus Zener Current (V_Z Up to 12 V)

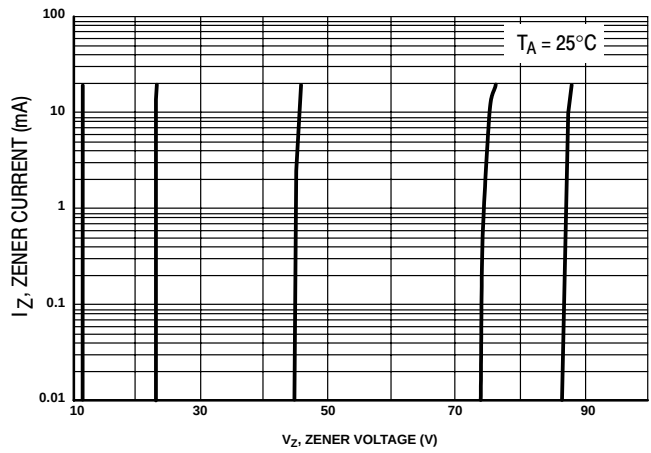


Figure 10. Zener Voltage versus Zener Current (12 V to 91 V)

INFORMATION FOR USING THE SOD-123 SURFACE MOUNT PACKAGE

MINIMUM RECOMMENDED FOOTPRINTS FOR SURFACE MOUNT APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to ensure proper solder connection interface between the board and the package.

The minimum recommended footprint for the SOD-123 is shown at the right.

The SOD-123 package can be used on existing surface mount boards which have been designed for the leadless 34 package style. The footprint compatibility makes conversion from leadless 34 to SOD-123 straightforward.

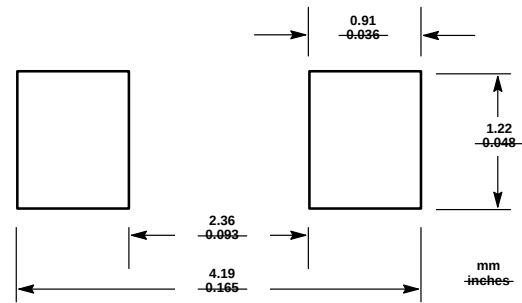


Figure 11. Minimum Recommended Footprint

SOD-123 POWER DISSIPATION

The power dissipation of the SOD-123 is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient; and the operating temperature, T_A . Using the values provided on the data sheet for the SOD-123 package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values

into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 0.37 watts.

$$P_D = \frac{150^\circ\text{C} - 25^\circ\text{C}}{340^\circ\text{C/W}} = 0.37 \text{ watts}$$

The 340°C/W for the SOD-123 package assumes using recommended footprint shown on FR-4 glass epoxy printed circuit board. Another alternative is to use a ceramic substrate or an aluminum core board such as Thermal Clad®. By using an aluminum core board material such as Thermal Clad, the power dissipation can be doubled using the same footprint.

GENERAL SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.

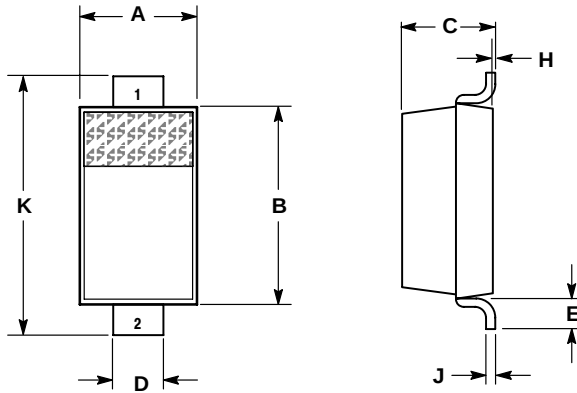
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling

* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

Zener Voltage Regulators – Surface Mounted

500 mW SOD–123

SOD–123
CASE 425–04
ISSUE C



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.055	0.071	1.40	1.80
B	0.100	0.112	2.55	2.85
C	0.037	0.053	0.95	1.35
D	0.020	0.028	0.50	0.70
E	0.01	---	0.25	---
H	0.000	0.004	0.00	0.10
J	---	0.006	---	0.15
K	0.140	0.152	3.55	3.85

STYLE 1:
PIN 1. CATHODE
2. ANODE

MMSZ4678T1 Series

Thermal Clad is a registered trademark of the Bergquist Company

ON Semiconductor and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada
Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center
4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-0031
Phone: 81-3-5740-2700
Email: r14525@onsemi.com

ON Semiconductor Website: <http://onsemi.com>

For additional information, please contact your local
Sales Representative.